

Product Change Notification - GBNG-10TTAV974

Date:

03 Jul 2019

Product Category:

Ethernet PHYs; Others

Affected CPNs:



Notification subject:

CCB 3782 Final Notice: Qualification of MTAI as an additional assembly site for selected Micrel products of the 0.18 um wafer technology at DBHU available in 48L TQFP (7x7x1.0mm) package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MTAI as an additional assembly site for selected Micrel products of the 0.18 um wafer technology at DBHU available in 48L TQFP (7x7x1.0mm) package.

Pre Change:

Assembled at ASE using CRM-1076WA die attach and G631H molding compound material.

Post Change:

Assembled at ASE using CRM-1076WA die attach and G631H molding compound material or assembled at MTAI using 3280 die attach and G700HA molding compound material.

Pre and Post Change Summary:

	Pre Change	Post C	Post Change					
			Microchip					
Assembly Site	ASE INC.	ASE INC.	Technology Thailan					
	(ASE)	(ASE)	(HQ)					
			(MTAI)					
Wire material	Au	Au	Au					
Die attach material	CRM-1076WA	CRM-1076WA	3280					
Molding compound	G631H	G631H	G700HA					
material	003111	003111	G70011A					
Lead frame material	C7025	C7025	C7025					

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MTAI as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

August 03, 2019 (date code: 1931)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and



post change parts.

Time Table Summary:

	June 2019			July 2019			August 2019								
Workweek	22	23	24	25	26	27	28	29	30	31	32	33	34	35	
Initial PCN Issue Date				X											
Qual Report Availability						X									
Final PCN Issue Date						X									
Estimated															
Implementation Date										^					

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

June 24, 2019: Issued initial notification.

July 03, 2019: Issued final notification. Attached the qualification report. Provided estimated first ship date EFSD to be on August 03, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_GBNG-10TTAV974_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

KSZ8041FTL

KSZ8041FTLI

KSZ8041FTLI-TR

KSZ8041FTL-S

KSZ8041FTL-TR

KSZ8041TL

KSZ8041TLI

KSZ8041TLI-S

KSZ8041TLI-TR

KSZ8041TL-TR

SPNY801037

SPNY801049

SPNY801066

SPNY801066-TR

SPNZ801037

SPNZ801037-TR

SPNZ801049

SPNZ801053

SPNZ801053-TR

SPNZ801066-TR

SPNZ801087

Date: Tuesday, July 02, 2019